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Dimensions

Chip Size	0402
L	1.02mm +0.15/-0.1mm (0.04 in +0.006/-0.004 in)
W	0.51mm +0.13/-0.1mm (0.02 in +0.005/-0.004 in)
T	0.64mm MAX (0.025 in MAX)
B	0.1mm MIN (0.004 in MIN)

Packaging Specifications

Packaging	Waffle
Packaging Quantity	368

General Information

Series	SMD MIL COG PRF32535
Style	SMD Chip
Description	SMD, Low ESR, MIL-PRF-32535
RoHS	Yes
Termination	Gold
Failure Rate	N/A
Qualifications	MIL-PRF-32535 M-Level
AEC-Q200	No
Shelf Life	78 Weeks
MSL	1

Specifications

Capacitance	33 pF
Capacitance Tolerance	5%
Voltage DC	50 VDC
Dielectric Withstanding Voltage	125 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	COG
Dissipation Factor	0.15% 1 MHz 25C
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms

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